

What is claimed is:

1. A polishing apparatus comprising:
a polishing table having a polishing surface;
5 a top ring for holding a substrate and pressing a
surface of the substrate against said polishing surface to
polish said surface of said substrate;
at least one optical measuring device disposed adjacent
to the outer peripheral portion of said polishing table and
10 below said polishing surface of said polishing table for
measuring the thickness of a layer formed on said surface of
said substrate; and
at least one notch formed in the peripheral portion of
said polishing table, said notch allowing light emitted from
15 said optical measuring device to pass therethrough and be
incident on said surface of said substrate and allowing light
reflected from said surface of said substrate to pass
therethrough and be incident on said optical measuring device.
- 20 2. A polishing apparatus according to claim 1, wherein
said substrate has a semiconductor device thereon.
- 25 3. A polishing apparatus according to claim 1, wherein
said top ring is swingable between an inner area and an outer
area on said polishing table so that the light emitted from
said optical measuring device is incident on a position
ranging from the outer circumferential edge to the central
portion of said substrate.

4. A polishing apparatus according to claim 1, wherein
when said top ring is swung to a maximum, the area of said
substrate which projects outwards beyond the outer
5 circumferential edge of said polishing table is not more than
40% of the entire area of said surface, being polished, of
said substrate.

5. A polishing apparatus according to claim 1, further
10 comprising a nozzle for supplying a cleaning liquid to said
optical measuring device.

6. A polishing apparatus comprising:
a polishing table having a polishing surface;
15 a top ring for holding a substrate to polish the
substrate by a relative motion between the substrate and said
polishing surface;
at least one optical measuring device for measuring the
thickness of a layer formed on said surface of the substrate
20 by applying light to said surface of the substrate; and
a moving mechanism for moving at least one of said top
ring and said polishing table during polishing operation;
wherein said moving mechanism moves said top ring or
said polishing table to the position where the central portion
25 of the substrate is exposed toward said optical measuring
device, for allowing said optical measuring device to measure
the central portion of the substrate.